

# SERIES 56i

## BOND HEADS

FLEXIBLE.  
AUTOMATIC.  
UNIQUE.

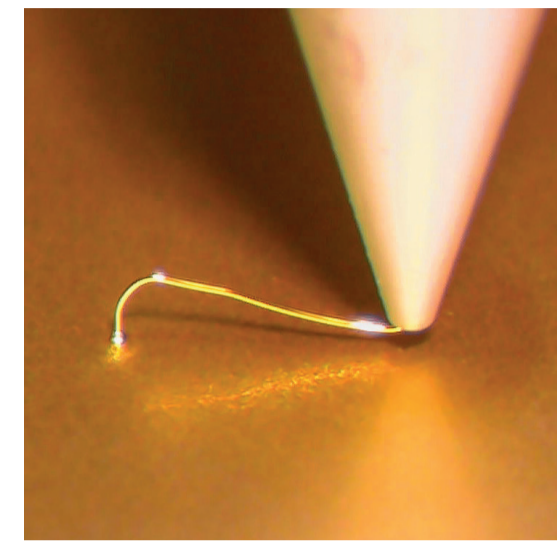
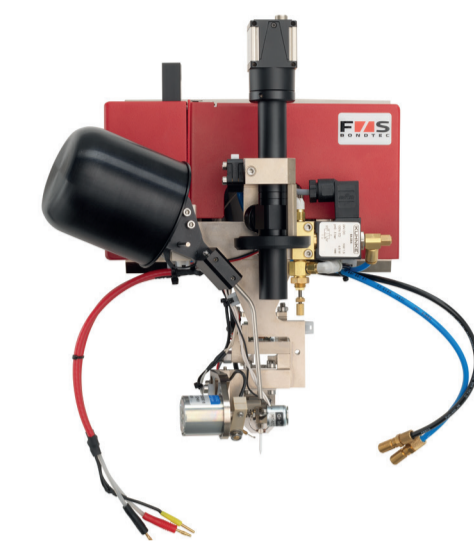


**56i**  
SERIES

**F7S**  
BONDTEC

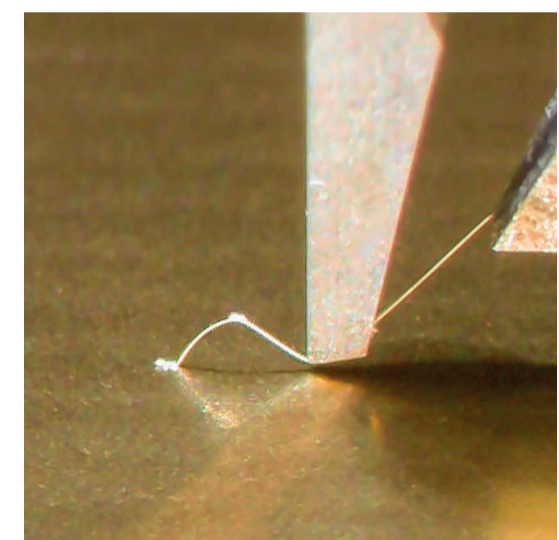
### 5610i – Gold Ball

- » Gold-Ball bonding for wires from 12 to 50  $\mu\text{m}$  diameter
- » Standard-Capillaries 16 mm to 19 mm
- » Bumping, Safety-Bump, Stitch-on-Ball



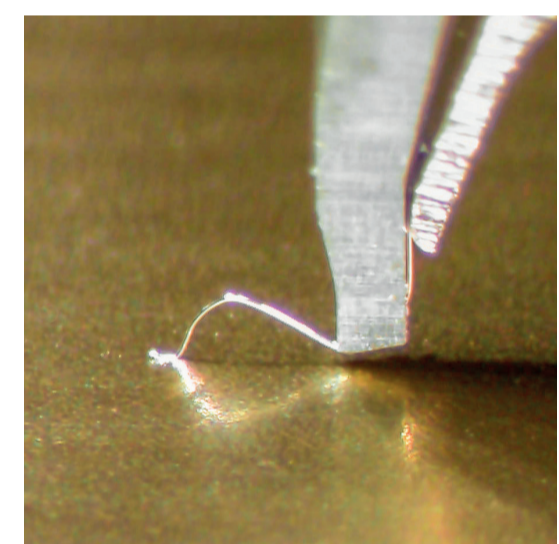
### 5630i – Wedge - Wedge

- » Wedge-Wedge bonding using 1" Tools Aluminum and Gold wires from 17.5 to 75  $\mu\text{m}$
- » 45° wire guide, retrofitable to 30° and 60°



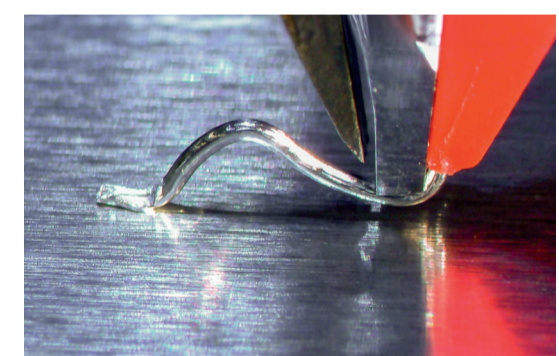
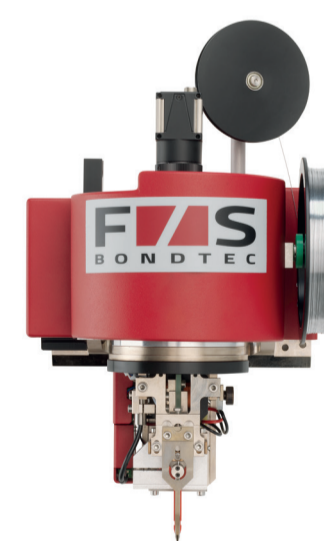
### 5632i – Deep Access

- » Wedge-Wedge bonding using 1" or 3/4" Tools
- » 90° wire guide for Aluminum, Gold wires from 12 to 75  $\mu\text{m}$  and ribbon up to 250x25  $\mu\text{m}$
- » Perfect for difficult and constricted bonding geometrics



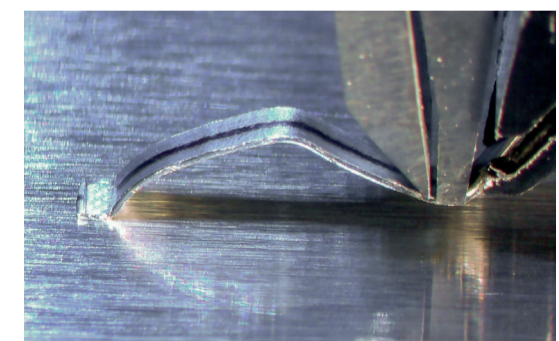
### 5650i – Heavy Wire

- » Wedge-Wedge bonding for Aluminum from 100 up to 500  $\mu\text{m}$  diameter // Copper from 100 up to 300  $\mu\text{m}$



### 5650i HR – Heavy Ribbon

- » Wedge-Wedge bonding for Aluminum ribbon until 2 mm



### 5600i – Pull- & Sheartester

- » Manual and automatic testing of thin and heavy wire bonds
- » Test head with easily changeable cartridges
- » **Patented solution** for automatic angle correction

